

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-301: General test methods for materials and assemblies - Soldering paste using fine solder particles

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN IEC 61189-5-301:2021 sisaldab Euroopa standardi EN IEC 61189-5-301:2021 ingliskeelset teksti.	This Estonian standard EVS-EN IEC 61189-5-301:2021 consists of the English text of the European standard EN IEC 61189-5-301:2021.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas.	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation and Accreditation.
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ICS 31.180

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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies - Part 5-301: General
test methods for materials and assemblies - Soldering paste
using fine solder particles
(IEC 61189-5-301:2021)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 5-301: Méthodes d'essai générales pour
les matériaux et les assemblages - Pâte à braser à fines
particules de brasage
(IEC 61189-5-301:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 5-
301: Allgemeine Prüfverfahren für Materialien und
Baugruppen - Lötpaste mit feinen Lötpartikeln
(IEC 61189-5-301:2021)

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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 91/1655/CDV, future edition 1 of IEC 61189-5-301, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-5-301:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-01-21
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61189-5-3	2015	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-3: General test methods for materials and assemblies - Soldering paste for printed board assemblies	EN 61189-5-3	2015
IEC 61190-1-2	2014	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly	EN 61190-1-2	2014
ISO 857-2	-	Welding and allied processes - Vocabulary - Part 2: Soldering and brazing processes and related terms	-	-

INTERNATIONAL STANDARD

NORME INTERNATIONALE



Test methods for electrical materials, printed boards and other interconnection structures and assemblies –

Part 5-301: General test methods for materials and assemblies – Soldering paste using fine solder particles

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –

Partie 5-301: Méthodes d'essai générales pour les matériaux et les assemblages – Pâte à braser à fines particules de brasage



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INTERNATIONAL STANDARD

NORME INTERNATIONALE



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Part 5-301: General test methods for materials and assemblies – Soldering paste using fine solder particles

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Partie 5-301: Méthodes d'essai générales pour les matériaux et les assemblages – Pâte à braser à fines particules de brasage

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ICS 31.180

ISBN 978-2-8322-9534-2

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 5-301: General test methods for materials and assemblies – Soldering paste using fine solder particles

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1655/CDV	91/1698/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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